

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC054N04NS G	**Issued**	21. August 2021
MA#	MA001335168		
Package	PG-TDSON-8-5	**Weight***	124.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.426	1.15	1.15	11496	11496
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		91	
	non noble metal	iron	7439-89-6	0.038	0.03		305	
	non noble metal	copper	7440-50-8	37.762	30.44	30.48	304369	304765
wire	non noble metal	copper	7440-50-8	0.048	0.04	0.04	384	384
encapsulation	organic material	carbon black	1333-86-4	0.096	0.08		772	
	plastics	epoxy resin	-	6.804	5.48		54845	
	inorganic material	silicondioxide	60676-86-0	41.018	33.06	38.62	330617	386234
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11701	11701
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1334	1334
solder	non noble metal	tin	7440-31-5	0.032	0.03		256	
	noble metal	silver	7440-22-4	0.040	0.03		320	
	non noble metal	lead	7439-92-1	1.518	1.22	1.28	12239	12815
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	iron	7439-89-6	0.022	0.02		180	
	non noble metal	copper	7440-50-8	22.292	17.97	18.00	179676	179910
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			27	
	non noble metal	iron	7439-89-6	0.011	0.01		91	
	non noble metal	copper	7440-50-8	11.320	9.12	9.13	91243	91361
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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